

25 Gbps 850 nm PIN

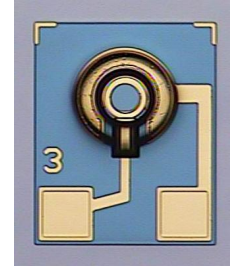
L-CR-IM00-00

Part Number: L-CR-IM00-00

Applications: 25 Gbps

Absolute Maximum Ratings (T = 25°C):

| Parameter | Symbol | Unit | Value |
|-----------------------|-----------|------|-----------|
| Forward Current | I_F | mA | 10 |
| Reverse Voltage | V_R | V | 40 |
| Reverse Current | I_R | mA | 1 |
| Operating Temperature | T_{op} | °C | 0 - 90 |
| Storage Temperature | T_{stg} | °C | -40 - 100 |



Electro-optical Characteristics (T = 25°C, unless noted otherwise):

| Parameter | Symbol | Unit | Min. | Typ. | Max. | Test Condition |
|-------------------|-----------|------|------|------|------|---|
| Aperture | D | μm | | 32 | | |
| Responsivity | R | A/W | | 0.5 | | $V_R = 5\text{ V}$ $\lambda = 850\text{ nm}$ |
| Dark Current | I_D | nA | | 0.1 | 1.0 | $V_R = 5\text{ V}$ |
| Breakdown Voltage | V_B | V | 50 | | | $I_R = 1\text{ }\mu\text{A}$ |
| Capacitance | C | pF | | 0.07 | 0.1 | $V_R = 2\text{ V}$ $f = 1\text{ MHz}$ |
| Peak Wavelength | λ | nm | | 850 | 860 | |
| Cut-off Frequency | f_c | GHz | | 22 | | $V_R = 2\text{ V}$ $R_L = 50\Omega$ |

Chip configuration:

- Both anode and cathode contacts on top (epi) surface.
- Dimension: 250 μm (width) x 300 μm (length) x 130 μm (thickness)
Tolerance: +/-12.5μm
- Bond pad size: 60 x 60 μm square
- P-bond pad on left